



Material Composition Sheet

Product: GS9023ACFY
 Package Type: LQFP-90/tray/Leadfree
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Die		31.60	Al	0.19	0.60	6013
			Si	31.41	99.39	993987
			Sub-total:	31.60	99.99	1000000
Die Attach		19.06	Ag	14.30	75.02	750262
			Epoxy Resin	4.76	24.97	249738
			Sub-total:	19.06	99.99	1000000
Lead Finish External		12.80	Bi	0.30	2.34	23438
			Sn	12.50	97.65	976563
			Sub-total:	12.80	99.99	1000001
Leadframe		141.07	Cu	136.00	96.40	964060
			Ni	4.50	3.18	31899
			Si	0.25	0.17	1772
			Zn	0.32	0.22	2268
			Sub-total:	141.07	99.97	999999
Marking Ink		0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound		554.13	Brominated flame ret	5.20	0.93	9384
			Epoxy Resin	56.80	10.25	102503
			Phenol Resin	56.80	10.25	102503
			Sb203	5.20	0.93	9384
			SiO2	426.00	76.87	768773
			Tetrabromobisphenol-A	4.13	0.74	7453
Sub-total:	554.13	99.97	1000000			
Wires		2.70	Au	2.70	100.00	1000000
			Sub-total:	2.70	100.00	1000000
Total:		761.37				

GENNUM CORPORATION

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